

# Amendments to the Claims

This listing of claims replaces all prior versions and listings of claims in the application:

22. (Currently amended) A method for fabricating electronics comprising:

- (a) freeing individual elements from a seed substrate; ~~and~~
- (b) inclining a different substrate; and
- (c) using gravitational forces and vibrational energy to place the individual elements in  
receptors formed in ~~a said~~ different substrate.

23. (Previously presented): The method of claim 22 wherein the individual elements are shaped as truncated cones and wherein the receptors are also shaped as truncated cones.

24. (Previously presented): The method of claim 22 wherein the different substrate is of a different material composition than is the seed substrate.

25. (Canceled)

26. (Previously presented): The method of claim 22 wherein the individual elements include circuit elements formed therein.

27. (Previously presented): The method of claim 26 wherein the circuit elements include a pixel.

28. (Previously presented): The method of claim 22 further including forming electrical conductors on said individual elements which are arranged to contact matching electrically conductive contacts formed in the receptors.

29. (Currently amended): The method of claim 28 further including applying an electrically conductive material inside said receptors so as to cover at least the electrically conductive contacts in said receptors, said electrically conductive material exhibiting increased conductivity in a direction normal to a major surface of said different substrate.

30. (Previously presented): The method according to Claim 22, wherein said step of applying said electrically conductive material includes applying and partially curing a unidirectionally conductive resin.

31. (Previously presented): The method according to Claim 30, wherein in said step of applying and partially curing said unidirectionally electrically conductive resin, said resin is applied by a method including steps of:

(a) coating said top surface of said new substrate and an inside area of said receptors with said unidirectionally electrically conductive resin; and

(b) removing said electrically conductive resin from said different substrate so that said unidirectionally electrically conductive resin remains only in said receptors.

32. (Previously presented): The method according to Claim 30, wherein said unidirectionally conductive resin is a Z-axis epoxy resin.

33. (Previously presented): The method according to Claim 22, further including monitoring placement of said individual elements in said receptors, said method for monitoring and correcting comprising steps of:

(a) applying voltage pulse waveforms to selected ones of the electrically conductive contacts;

(b) measuring current pulse or pulses generated as a result of said applying of said voltage pulse waveforms; and

(c) repeating said steps of applying of said voltage pulse waveforms and of measuring of said current pulse for each receptor.

34. (Currently amended): The method according to Claim 33, further including, in case of absence of said current pulse, steps of:

- (i) pouring individual elements onto said different substrate;
- (ii) again using gravitational forces and/or vibrational energy to place the poured individual elements into open receptors formed in said different substrate;
- (iii) removing of unreceived and/or improperly received individual elements;
- (iv) applying said voltage pulse waveforms to selected ones of the electrically conductive contacts;
- (v) measuring for said current pulse or pulses; and
- (vi) repeating said steps (i)-(v) until all said receptors are properly filled with said individual elements.